

Amendments to the Claims:

Claims 1 and 3 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A method for connecting a vertically ~~horizontally~~ stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, using a cage having an open side, comprising:
providing a plurality of primary integrated circuit packages, each primary integrated circuit package having a plurality of peripheral sides, a top, and a bottom and having a plurality of leads extending from one peripheral side thereof;
providing the cage including two open ends ~~an open~~ top, an open bottom, and at least three attached adjacent peripheral sides ~~and two other peripheral sides, each of the two other peripheral sides attached to one of two of the at least three attached adjacent peripheral sides, one interior wall of one side of the attached adjacent peripheral sides having a plurality of conductive buses located thereon,~~ the cage enclosing at least three adjacent peripheral sides of the plurality of sides of each primary integrated circuit package of the vertically stacked plurality of primary integrated circuit packages; and
adhesively attaching the cage to the substrate, the cage connecting at least one lead extending from a peripheral side of at least one integrated circuit package of the plurality of outer leads of the vertically stacked plurality of primary integrated circuit packages to at least one circuit of the substrate ~~conductive bus of a plurality of spaced transverse conductive buses.~~

2. (Canceled)

3. (Currently Amended) A method for connecting a vertically ~~horizontally~~ stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads on a side thereof of a plurality of sides, comprising:

providing a cage including ~~an open top~~, an open bottom, at least three attached adjacent

~~peripheral sides and portions of a fourth peripheral side attached to each of two of the at least three attached adjacent peripheral sides, one interior wall of one side of the attached adjacent peripheral sides having a plurality of conductive buses located thereon, the cage enclosing at least three adjacent sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages, each primary integrated circuit package having opposed leads extending from a side opposed sides thereof; and~~

attaching the cage to the substrate by adhesive attachment of the edge of each of two of the three

peripheral sides of the cage to the substrate, the cage connecting at least one lead extending from a peripheral side of at least one integrated circuit package of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to at least one circuit of the substrate ~~conductive bus of a plurality of spaced transverse conductive buses.~~

4. (Withdrawn) A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, comprising:

providing a cage enclosing at least three sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and attaching the cage to the substrate using one of adhesive and snap pins fitting in holes in the substrate, the cage connecting at least one outer lead of the plurality of outer leads of the stacked plurality of primary integrated circuit packages to at least one conductive bus of a plurality of spaced transverse conductive buses, with a portion of a semi-continuous flexible tape located within the cage.